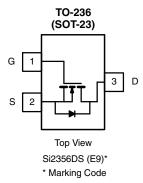




# N-Channel 40 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}\left(\Omega\right)$ Max.	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)			
	0.051 at V <sub>GS</sub> = 10 V	4.3				
40	0.054 at V <sub>GS</sub> = 4.5 V	4.1	3.8 nC			
	0.070 at V <sub>GS</sub> = 2.5 V	3.6				



### **Ordering Information:**

Si2356DS-T1-GE3 (Lead (Pb)-free and Halogen-free)

#### **FEATURES**

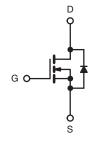
- TrenchFET® Power MOSFET
- 100 % R<sub>q</sub> Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



HALOGEN **FREE** 

#### **APPLICATIONS**

- DC/DC Converter
- Load Switch
- LED Backlighting
- **Power Management**



N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATIN</b>	<b>GS</b> (T <sub>A</sub> = 25 °C	, unless otherw	vise noted)	
Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V <sub>DS</sub>	40	V
Gate-Source Voltage		V <sub>GS</sub>	± 12	v
	T <sub>C</sub> = 25 °C		4.3	
Continuous Drain Current (T = 150 °C)	T <sub>C</sub> = 70 °C		3.4	
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	3.2 <sup>a,b</sup>	
	T <sub>A</sub> = 70 °C		2.6 <sup>a,b</sup>	Α
Pulsed Drain Current (t = 100 μs)		I <sub>DM</sub>	20	
0 " 0 0 0 0	T <sub>C</sub> = 25 °C		1.4	
Continuous Source-Drain Diode Current	T <sub>A</sub> = 25 °C	l <sub>S</sub>	0.8 <sup>a,b</sup>	
	T <sub>C</sub> = 25 °C		1.7	
Mariana Barra Birata di a	T <sub>C</sub> = 70 °C		1.1	
Maximum Power Dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.96 <sup>a,b</sup>	W
	T <sub>A</sub> = 70 °C		0.62 <sup>a,b</sup>	
Operating Junction and Storage Temperature	e Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C

THERMAL RESISTANCE RATINGS								
Parameter	Symbol	Typical	Maximum	Unit				
Maximum Junction-to-Ambient a,c	t ≤ 5 s	R <sub>thJA</sub>	100	130	°C/W			
Maximum Junction-to-Foot (Drain)	Steady State	$R_{thJF}$	60	75				

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 5 s.
- c. Maximum under steady state conditions is 175  $^{\circ}\text{C/W}.$

Document Number: 62893 S13-1814-Rev. A, 12-Aug-13 For technical questions, contact: pmostechsupport@vishav.com



<b>SPECIFICATIONS</b> (T <sub>J</sub> = 25 °C,			NA'	T	N4	11	
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	40		1		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$v_{GS} = 0 \text{ v}, I_D = 250 \mu\text{A}$	40	40		V	
V <sub>DS</sub> Temperature Coefficient	ΔV <sub>DS</sub> /T <sub>J</sub>	I <sub>D</sub> = 250 μA		43		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	V V 1 050 A		- 3.8			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_{D} = 250 \mu\text{A}$	0.6		1.5	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$			1	μΑ	
	500	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μ, .	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α	
		$V_{GS} = 10 \text{ V}, I_D = 3.2 \text{ A}$		0.042	0.051		
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 3.1 \text{ A}$		0.045	0.054	Ω	
		$V_{GS} = 2.5 \text{ V}, I_D = 2 \text{ A}$		0.056	0.070		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 3.2 \text{ A}$		13		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			370		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		50			
Reverse Transfer Capacitance	C <sub>rss</sub>			17			
·	Qg	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.2 \text{ A}$		8.1	13	nC	
Total Gate Charge		V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 3.2 A		3.8	5.7		
Gate-Source Charge	Q <sub>gs</sub>			0.72			
Gate-Drain Charge	Q <sub>gd</sub>			0.81			
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.2	0.7	1.4	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			6	12		
Rise Time	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, R_1 = 7.7 \Omega$		12	20	_	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 2.6 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		13	20		
Fall Time	t <sub>f</sub>	3		6	12	1	
Turn-On Delay Time	t <sub>d(on)</sub>			10	20	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = 20 \text{ V, R}_{1} = 7.7 \Omega$		52	78		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 2.6 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_a = 1 \Omega$		18	27		
Fall Time	t <sub>f</sub>	5 32.1 g		53	80		
Drain-Source Body Diode Characteristic	-						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			1.4		
Pulse Diode Forward Current (t = 100 μs)	I <sub>SM</sub>	-			20	Α	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 2.6 A, V <sub>GS</sub> = 0 V		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	, do		12	20	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			5	10	nC	
Dody Diodo Hovoroc Hoodvery Orlarge		$I_F = 2.6 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$			0	110	
Reverse Recovery Fall Time	t <sub>a</sub>			8.5		I	

#### Notes:

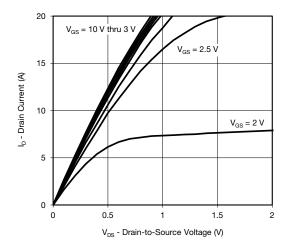
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$ 

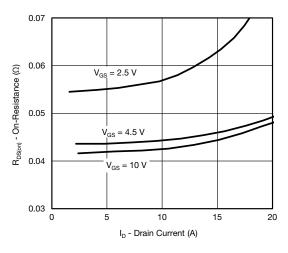
b. Guaranteed by design, not subject to production testing.



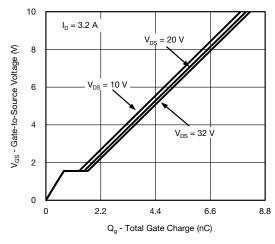
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



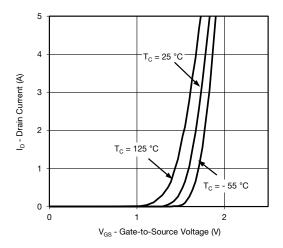
#### **Output Characteristics**



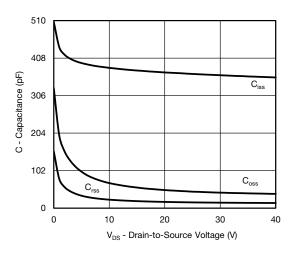
On-Resistance vs. Drain Current and Gate Voltage



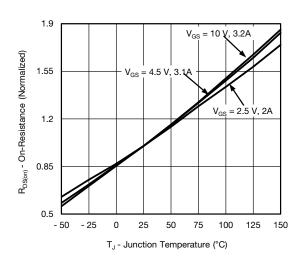
Gate Charge



**Transfer Characteristics** 

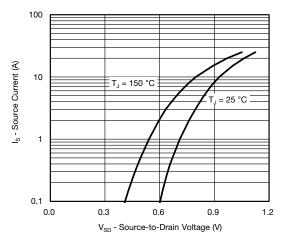


Capacitance

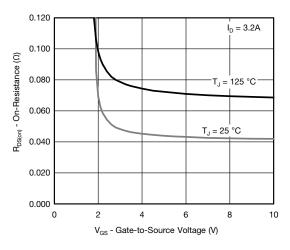


On-Resistance vs. Junction Temperature

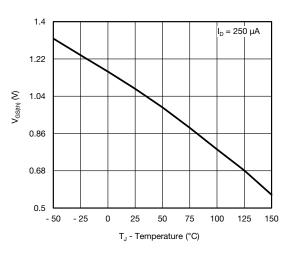
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



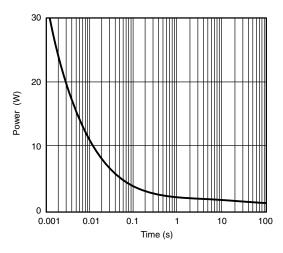
Source-Drain Diode Forward Voltage



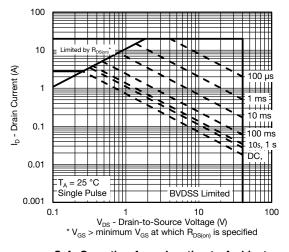
On-Resistance vs. Gate-to-Source Voltage



**Threshold Voltage** 



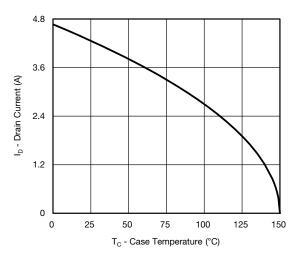
Single Pulse Power (Junction-to-Ambient)



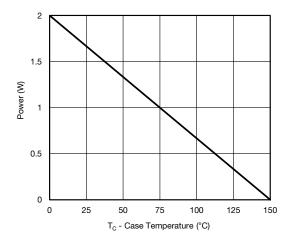
Safe Operating Area, Junction-to-Ambient



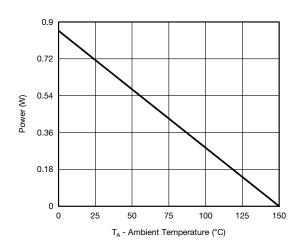
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



#### **Current Derating\***



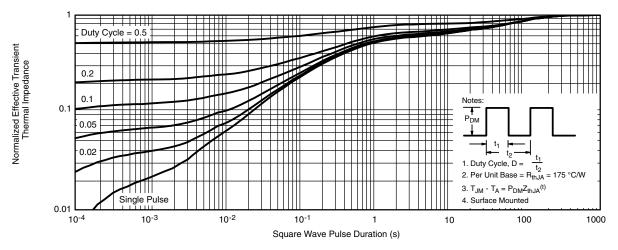




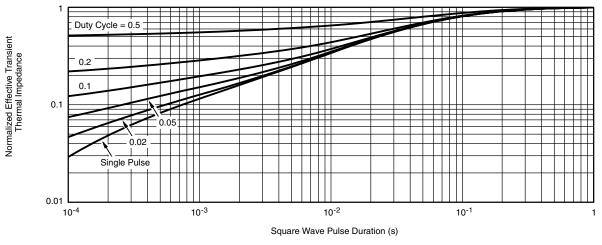
Power Junction-to-Ambient

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max.)}$  = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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## SOT-23 (TO-236): 3-LEAD







Dim	MILLI	METERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.9	5 BSC 0.03		74 Ref	
e <sub>1</sub>	1.90 BSC 0.0748 Ref		8 Ref		
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
FCN: S-03946-Rev K 09-	lul-01	•			

ECN: S-03946-Rev. K, 09-Jul-01

DWG: 5479

Document Number: 71196 www.vishay.com 09-Jul-01



### **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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